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Intellectual Property Protection in Printed Board Manufacturing

Supersedes IPC-1071A

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A standard developed by IPC

Association Connecting Electronics Industries



The Principles of Standardization

In May 1995 the IPC's Technical Activities Executive Committee (TAEC) adopted Principles of Standardization as a guiding principle of IPC's standardization efforts.

Standards Should:

- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Intellectual Property Protection in Printed Board Manufacturing

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the Intellectual Property Standard Committee (E-20) of IPC

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Users of this publication are encouraged to participate in the
development of future revisions.

Contact:

IPC
3000 Lakeside Drive, Suite 105N
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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Intellectual Property Standard Committee	PB Fab Intellectual Property Subcommittee	Technical Liaison of the IPC Board of Directors
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Intellectual Property Protection in Printed Board Manufacturing

1 SCOPE

1.1 Purpose The purpose of this standard is to assist printed board (PB) manufacturers in the development of requirements for the protection of intellectual property (IP) for their customers in commercial, industrial and military and other high-reliability markets. This standard focuses on protection of the inherent IP designed into the PB such that IP flows from the customer to the PB manufacturer and that IP incorporated into the PB is protected. Patent and other such “forever protection” of the manufactured product is beyond the scope of this document.

This standard is not intended to be a legal guide. Please consult an attorney for questions of a legal nature.

1.2 Levels of IP Protection This standard recognizes that electrical and electronic products are subject to classifications by intended end-item use. Additionally, different manufacturers and/or customers may desire different levels of IP protection. Three levels of IP protection have been established to reflect the differences in IP protection.

1.2.1 Definition of Requirements The words “shall” and “shall not” are used in the text of this document where there is a requirement for IP protection.

1.3 Selection of IP Level The user is responsible for selecting the desired level of IP protection. The procurement documentation or data package shall state the IP level and any exceptions to specific parameters, where appropriate.

Criteria defined in this document reflect three levels of protection, which are as follows in 1.3.1 through 1.3.3.

1.3.1 Level 1 – Basic IP Protection This level of requirements provides good IP protection and is best suited for high-volume consumer goods. Items may be manufactured globally under Level 1 IP protection.

1.3.2 Level 2 – High IP Protection This level of requirements provides a higher level of IP protection and is best suited for high-value goods. In most cases, items may be manufactured globally under Level 2 IP protection.

1.3.3 Level 3 – Advanced Level for Military, Government and Commercial IP Protection This level of requirements provides the highest IP protection and is best suited for military and other high-security systems.

- a. Level 3 activities required to be conducted in the United States (U.S.) or in a State Department- and Department of Defense- (or other appropriate government agency) approved location shall be under the strict supervision of U.S. citizens or those possessing legal U.S. residency.
- b. For Level 3 activities conducted for a different national government, the user shall adhere to all citizenship and residency requirements, regulations and laws of that national government.

2 APPLICABLE DOCUMENTS

2.1 IPC¹

IPC-T-50 Terms and Definitions for Interconnecting and Packaging Electronic Circuits

2.2 International Traffic in Arms Regulations (ITAR) ITAR is a set of extraterritorial U.S. government regulations that implement the provisions of The Arms Export Control Act (AECA), as prescribed in 22 CFR Parts 120-130.² ITAR regulates the permanent and temporary export, re-export and temporary import of defense articles, technical data and defense services on the U.S. Munitions List (USML). The Department of State’s Directorate of Defense Trade Controls (DDTC) interprets and enforces the ITAR. Its goal is to safeguard U.S. national security and to further U.S. foreign policy objectives.

1. <http://www.ipc.org>

2. <http://www.ecfr.gov>